## Features

- Halogen-free package has underwriters

Laboratory Flammability Classification 94V-0

- Thin package: thickness 1.0 mm
- Low forward voltage, high efficiency


Package: POWER QFN5x6

## Mechanical Data

- Case: epoxy, molded
- Weight: 0.1grams (approximately)
- Finish: all external surfaces corrosion resistant and terminal leads readily solderable
- Lead temperature for soldering purpose: $260^{\circ} \mathrm{C}$ max. for 10 sec

- 3000 pcs/reel


## Maximum Ratings \& Electrical Characteristics

( $\mathrm{T}_{\mathrm{A}}=25^{\circ} \mathrm{C}$ unless otherwise noted)

|  | Parameter | Test Conditions |  | Symbol | Value | Unit |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| Maximum Repetitive Peak Reverse Voltage |  |  |  | VRrm | 200 | V |
| Working Peak Reverse Voltage |  |  |  | VRWm | 200 | V |
| Maximum DC Blocking Voltage |  |  |  | Vdc | 200 | V |
| Maximum Average Forward Rectified Current <br> @ $\mathrm{T}_{\mathrm{c}}=105^{\circ} \mathrm{C}$ |  |  |  | IF(AV) | 3.0 | A |
| Peak Forward Surge Current 8.3 ms Single Half Sine-wave Superimposed on Rated Load per Diode |  |  |  | IFSM | 70 | A |
| Peak repetitive Reverse Current Per Leg at $\mathrm{tp}=2.0 \mu \mathrm{~s}, 1 \mathrm{KHz}$ |  |  |  | $\mathrm{I}_{\text {RRM }}$ | 0.5 | A |
| Operating Junction Temperature Range |  |  |  | TJ | - 55 to +150 | ${ }^{\circ} \mathrm{C}$ |
| Storage Temperature Range |  |  |  | Tstg | - 55 to +150 | ${ }^{\circ} \mathrm{C}$ |
| Maximum Instantaneous Forward Voltage per Leg |  | $\begin{aligned} & I_{F}=3 A \\ & I_{F}=3 A \end{aligned}$ | $\begin{aligned} & \mathrm{Tc}=25^{\circ} \mathrm{C} \\ & \mathrm{Tc}=125^{\circ} \mathrm{C} \end{aligned}$ | $V_{F}$ | $\begin{aligned} & 0.92 \\ & 0.87 \end{aligned}$ | V |
| Maximum Reverse Current per Leg at Working Peak Reverse Voltage |  |  | $\begin{aligned} & \mathrm{T} \jmath=25^{\circ} \mathrm{C} \\ & \mathrm{~T}=100^{\circ} \mathrm{C} \end{aligned}$ | IR | $\begin{gathered} 200 \\ 15 \end{gathered}$ | $\mu \mathrm{A}$ <br> mA |
| Thermal Characteristics ( $\mathrm{T}_{\mathrm{A}}=25^{\circ} \mathrm{C}$ unless otherwise noted) |  |  |  |  |  |  |
| Symbol | Parameter | Typ. (POWER QFN5x6) |  |  |  | Unit |
| $\mathrm{R}_{\text {өJc }}$ | Thermal Resistance, Junction to Case per Leg | 2.5 |  |  |  | ${ }^{\circ} \mathrm{C} / \mathrm{W}$ |
| $\mathrm{R}_{\text {өJA }}$ | Thermal Resistance, Junction to Ambient per Leg | 50 |  |  |  | ${ }^{\circ} \mathrm{C} / \mathrm{W}$ |

Note: Pulse test:300us pulse width, duty cycle=2\%

## MBRP3200

Schottky Barrier Rectifier
SEMICONDUCTOR

## Ratings and Characteristics Curves ( $\mathrm{T}_{\mathrm{A}}=25^{\circ} \mathrm{C}$ unless otherwise noted)




Figure 3. Typical Forward Characteristics

FIG. 2 MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT



Figure 4. Typical Reverse Characteristics

## Package Outline Dimensions

in millimeters
POWER QFN5x6


